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PATENT NUMBER and
ISSUE DATE

U.S. UTILITY Patent Application

APPL NUM 10069404	FILING DATE 05/06/2002	CLASS 252	SUBCLASS 79.1	GAU 1765	EXAMINER Umez-Eronini
**APPLICANTS: Uchida Takeshi; Kamigata Yasuo; Terasaki Hiroki; Kurata Yasushi; Hoshino Tetsuya; Igarashi Akiko;					
**CONTINUING DATA VERIFIED: THIS APPLICATION IS A 371 OF PCT/JP00/05765 08/25/2000					
** FOREIGN APPLICATIONS VERIFIED: JAPAN HEI11-239777 08/26/1999 JAPAN HEI11-239778 08/26/1999 JAPAN HEI11-239779 08/26/1999					
PG-PUB <input type="checkbox"/> DO NOT PUBLISH <input type="checkbox"/>		RESCIND <input type="checkbox"/>			
Foreign priority claimed <input type="checkbox"/> yes <input type="checkbox"/> no		35 USC 119 conditions met <input type="checkbox"/> yes <input type="checkbox"/> no		ATTORNEY DOCKET NO 566.41259X00	
Verified and Acknowledged Examiners's initials					
TITLE : Polishing compound for chemimechanical polishing and polishing method					
U.S. DEPT. OF COMM./PAT. & TM-PTO-436L (Rev. 12-94)					

NOTICE OF ALLOWANCE MAILED		CLAIMS ALLOWED	
		Total Claims	Print Claim for 0.0
ISSUE FEE		DRAWING	
Amount Due	Date Paid	Sheets Drwg.	Figs. Drwg. Print Fig.
<input type="checkbox"/> TERMINAL DISCLAIMER		Application Examiner	
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